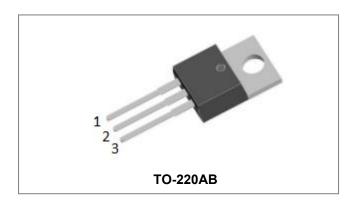






# **MBR3080CT SCHOTTKY RECTIFIER**



#### **Features**

- 150°C T<sub>J</sub> operation
- Center tap configuration
- Low forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced
- mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- This is a Pb Free Device
- . All SMC parts are traceable to the wafer lot
- · Additional testing can be offered upon request

### **Circuit Diagram**



### **Applications**

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

### **Maximum Ratings:**

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage	$V_{RRM}$	-		
Working Peak Reverse Voltage	$V_{RWM}$		80	V
DC Blocking Voltage	$V_R$			
Average Rectified Forward Current	I <sub>F (AV)</sub>	50% duty cycle @Tc=100°C, rectangular wave form	15(Per Leg) 30(Per Device)	Α
Peak One Cycle Non-Repetitive Surge Current(Per Leg)	I <sub>FSM</sub>	8.3ms, Half Sine pulse, T <sub>C</sub> = 25 °C	220	Α

#### **Electrical Characteristics:**

Characteristics	Symbol	Condition	Тур.	Max.	Units
Forward Voltage Drop(Per Leg)*	V <sub>F1</sub>	@ 15A, Pulse, T <sub>J</sub> = 25 °C	0.63	0.745	V
	V <sub>F2</sub>	@ 15A, Pulse, T <sub>J</sub> = 125 °C	0.58	0.625	V
Reverse Current(Per Leg)*	I <sub>R1</sub>	$@V_R = rated V_{R,} T_J = 25 °C$	0.03	1.0	mA
	I <sub>R2</sub>	$@V_R = \text{rated } V_R, T_J = 125  ^{\circ}\text{C}$	15	25	mA
Junction Capacitance(Per Leg)	Ст	@V <sub>R</sub> = 5V, T <sub>C</sub> = 25 °C f <sub>SIG</sub> = 1MHz	300	700	pF
Series Inductance(Per Leg)	Ls	Measured lead to lead 5 mm from package body	8.0	-	nH
Voltage Rate of Change	dv/dt	-	-	10,000	V/μs

<sup>\*</sup> Pulse width < 300 µs, duty cycle < 2%

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Junction Capacitance-CT(PF)

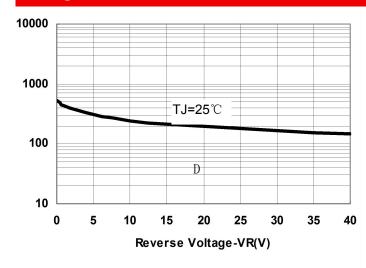




# **Thermal-Mechanical Specifications:**

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	TJ	-	-55 to +150	°C
Storage Temperature	T <sub>stg</sub>	-	-55 to +150	°C
Typical Thermal Resistance Junction to Case	R <sub>θJC</sub>	DC operation	3	°C/W
Typical Thermal	R <sub>θJS</sub>	DC operation	60	°C/W
Resistance, Case to Heat Sink				
Approximate Weight	wt	-	2	g

## **Ratings and Characteristics Curves**



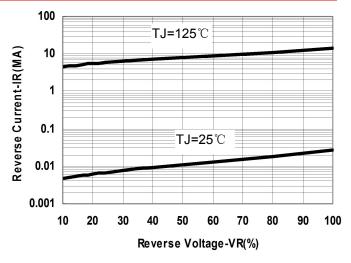


Fig.1-Typical Junction Capacitance

Fig.2-Typical Reverse Characteristics

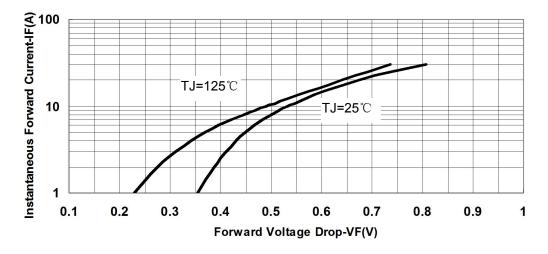


Fig.3-Typical Instantaneous Forward Voltage Characteristics

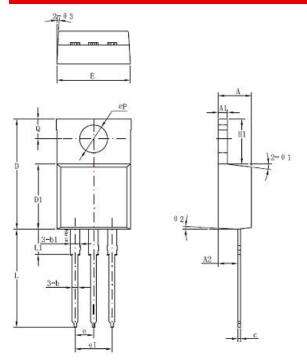
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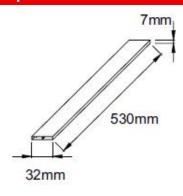


### **Mechanical Dimensions TO-220AB**



	Dimensions in millimeters		
Symbol			
	Min	Typical	Max
Α	4.42	4.57	4.72
A1	1.17	1.27	1.37
A2	2.52	2.69	2.89
b	0.71	0.81	0.96
b1	1.17	1.27	1.37
С	0.31	0.38	0.61
D	14.94	15.24	15.54
D1	8.85	9.00	9.15
E	10.01	10.16	10.31
е		2.54	
e1	4.98	5.06	5.18
H1	6.04	6.24	6.44
L	12.7	13.56	13.80
L1	3.56	3.5	3.96
ФР	3.74	3.84	4.04
Q	2.54	2.74	2.94
Θ1		7°	
Θ2		3°	
Θ3		4°	

# **Tube Specification**



# **Marking Diagram**



Where XXXXX is YYWWL

MBR = Device Type 30 = Forward Current (30A) 80 = Reverse Voltage(80V) CT = Configuration

 SSG
 = SSG

 YY
 = Year

 WW
 = Week

 L
 = Lot Number

Cautions: Molding resin Epoxy resin UL:94V-0

## **Ordering Information**

Device	Package	Shipping	
MBR3080CT	TO-220AB (Pb-Free)	50 pcs/ tube	

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

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